*NOTES:

1. Cx1 was added to the design later in the project. It is kluged onto the board, since it does not have a placeholder on the PCB.

2. R13 is x3 paralleled (stacked) 9.76 ohm 1/4W 1206-package resistors. These 3 resistors can be replaced by a single 3.3 ohm 5% or 3.32 ohm 1% 2010-package resistor.

3. C14 can be replaced by a 50V or 100V rated capacitor with all other parameters being equal (i.e. 2200pF capacitance, 0805-package or larger, and COG temp. coefficient).
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